IPC ASSOCIATION CONNECT ELECTRONICS INDUSTR	Material Compos © Copyright 2005. IPC international and Pan-A	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					Informati	ion	
upplier Infor													
Company name*			Company unique ID			Unique ID Authority				Response Date*			
onsemi										2025-05-14			
Contact Name			Title - Contact			Phone - Contact*				Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			Phone - Representative*				Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Reques	ster Item Number	Mfr Item Number	er Mfr Item Name	Mfr Item Name		Effective Date	Version	N	Ianufacturing Site	W	eight*	UOM	Unit Type
		MT9V124EBKSTC- VGA 1/13		13 SOC		2025-05-14 CP2		P2	10.773		mg	Each	
Ianufacturin s	g Proccess Informatio	on											
Terminal Plating / Grid Array Material			Ferminal Base Alloy J-STD-020 MSI		L Rating	Peak Process Body Temperature Max Time at Pe		e Max Time at Peak	ık Temperature Number of Reflow Cycles				
SnAgCu		CU Allo	CU Alloy 3			260	C 3		30	seconds	3		
omments													
TTENTION: MS	SL 3 Rated item requires I	Bake and Dry Pacl	k (after electrical test)										
or more informa	tion regarding material co	omposition please	refer to page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of					
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the					

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.69	mg		Misc.	proprietary data		0.0064	mg
			Supplier	Silicon (Si)	7440-21-3		1.6668	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0167	mg
Die Attach	0.16	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.096	mg
			Supplier	Epoxy resins	129915-35-1		0.032	mg
			Supplier	Acrylic resins	Proprietary Data		0.032	mg
Electrode	0.17	mg	Supplier	Titanium (Ti)	7440-32-6		0.0001	mg
			В	Nickel (Ni)	7440-02-0		0.1012	mg
			Supplier	Gold (Au)	7440-57-5		0.0041	mg
			Supplier	Copper (Cu)	7440-50-8		0.0025	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0621	mg
Glass Lid /Cap	7.89	mg	Supplier	Boron Trioxide (B2O3)	1303-86-2		1.1204	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		4.4815	mg
			Supplier	Barium Monoxide (BaO)	1304-28-5		0.6312	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.8679	mg
			Supplier	Calcium Monoxide (CaO)	1305-78-8		0.789	mg
Lid Attach	0.003	mg		Photoinitiator	proprietary data		0.0008	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.0022	mg
Solder Ball	0.14	mg	Supplier	Silver (Ag)	7440-22-4		0.0042	mg
			Supplier	Tin (Sn)	7440-31-5		0.1351	mg
			Supplier	Copper (Cu)	7440-50-8		0.0007	mg
Substrate and Solder Mask	0.72	mg	Supplier	Silica crystalline	14808-60-7, 14464- 46-1		0.072	mg
			Supplier	Cured Resin of Solder Mask	Proprietary Data		0.342	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data		0.306	mg